

NCE P-Channel Enhancement Mode Power MOSFET

Description

The NCE3407 uses advanced trench technology to provide excellent $R_{DS(ON)}$, This device is suitable for use as a load switch or in PWM applications.

General Features

• $V_{DS} = -30V, I_{D} = -4.1A$

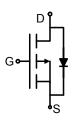
 $R_{DS(ON)}$ < 95m Ω @ V_{GS} =-4.5V

 $R_{DS(ON)}$ < 65m Ω @ V_{GS} =-10V

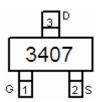
- High power and current handing capability
- Lead free product is acquired
- Surface mount package

Application

- PWM applications
- Load switch
- Power management



Schematic diagram



Marking and pin assignment



SOT-23 top view

Package Marking and Ordering Information

Device Marking	Device	Device Package	Reel Size	Tape width	Quantity
3407	NCE3407	SOT-23	Ø180mm	8 mm	3000 units

Absolute Maximum Ratings (T_A=25 ℃unless otherwise noted)

Parameter	Symbol	Limit	Unit
Drain-Source Voltage	V _{DS}	-30	V
Gate-Source Voltage	V _{GS}	±20	V
Drain Current-Continuous	I _D	-4.1	Α
Drain Current-Pulsed (Note 1)	I _{DM}	-20	Α
Maximum Power Dissipation	P _D	1.4	W
Operating Junction and Storage Temperature Range	T_{J} , T_{STG}	-55 To 150	°C

Thermal Characteristic

Thermal Resistance, Junction-to-Ambient (Note 2)	$R_{ heta JA}$	90	°C/W

Electrical Characteristics (T_A=25°C unless otherwise noted)

Parameter	Symbol	Condition	Min	Тур	Max	Unit
Off Characteristics						
Drain-Source Breakdown Voltage	BV _{DSS}	V _{GS} =0V I _D =-250μA	-30	-33	-	V
Zero Gate Voltage Drain Current	I _{DSS}	V _{DS} =-24V,V _{GS} =0V	-	-	-1	μA



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Parameter	Symbol	Condition	Min	Тур	Max	Unit
Gate-Body Leakage Current	I _{GSS}	V _{GS} =±20V,V _{DS} =0V	-	-	±100	nA
On Characteristics (Note 3)	•			•		
Gate Threshold Voltage	$V_{GS(th)}$	$V_{DS}=V_{GS}$, $I_{D}=-250\mu A$	-1	-1.5	-3	V
Danie Course On Otata Basistana	R _{DS(ON)}	V _{GS} =-10V, I _D =-4.1A	-	48	65	mΩ
Drain-Source On-State Resistance		V _{GS} =-4.5V, I _D =-4A	-	60	95	mΩ
Forward Transconductance	g FS	V _{DS} =-5V,I _D =-4.1A	5.5	-	-	S
Dynamic Characteristics (Note4)	•					
Input Capacitance	C _{lss}	\/ 45\/\/ O\/	-	650	-	PF
Output Capacitance	C _{oss}	- V _{DS} =-15V,V _{GS} =0V, - F=1.0MHz	-	105	-	PF
Reverse Transfer Capacitance	C _{rss}	F=1.UIVITZ	-	65	-	PF
Switching Characteristics (Note 4)	<u> </u>			•		
Turn-on Delay Time	t _{d(on)}		-	8.5	-	nS
Turn-on Rise Time	t _r	V_{DD} =-15V,R _L =3.6 Ω	-	4.5	-	nS
Turn-Off Delay Time	t _{d(off)}	V_{GS} =-10V, R_{GEN} =3 Ω	-	26	-	nS
Turn-Off Fall Time	t _f		-	12.5	-	nS
Total Gate Charge	Qg		-	12.5	-	nC
Gate-Source Charge	Q _{gs}	V _{DS} =-15V,I _D =-4A,V _{GS} =-10V	-	2.8	-	nC
Gate-Drain Charge	Q_{gd}	1	-	2.7	-	nC
Drain-Source Diode Characteristics	•	•		1		1
Diode Forward Voltage (Note 3)	V _{SD}	V _{GS} =0V,I _S =-4.1A	-	-	-1.2	V

Notes:

- $\textbf{1.} \ \textbf{Repetitive Rating: Pulse width limited by maximum junction temperature.}$
- **2.** Surface Mounted on FR4 Board, $t \le 10$ sec.
- 3. Pulse Test: Pulse Width ≤ 300µs, Duty Cycle ≤ 2%.
- 4. Guaranteed by design, not subject to production

Typical Electrical and Thermal Characteristics

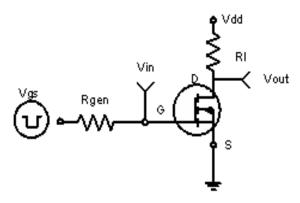


Figure 1:Switching Test Circuit

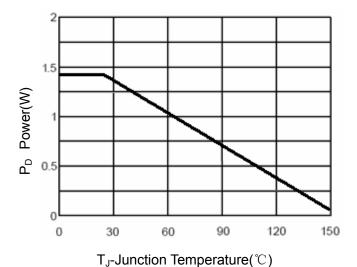


Figure 3 Power Dissipation

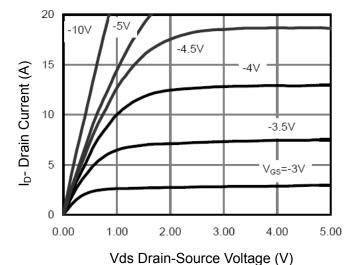


Figure 5 Output Characteristics

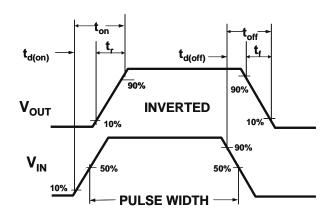


Figure 2:Switching Waveforms

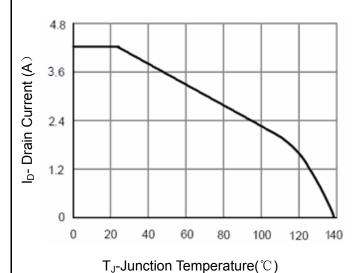


Figure 4 Drain Current

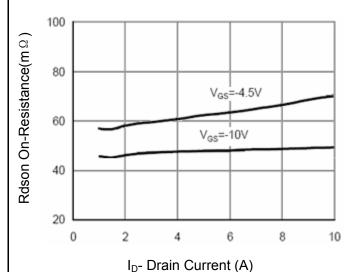


Figure 6 Drain-Source On-Resistance

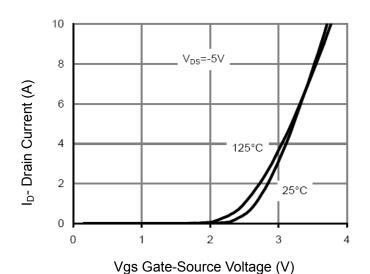
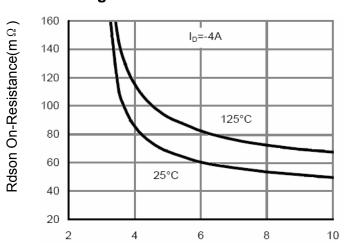


Figure 7 Transfer Characteristics



Vgs Gate-Source Voltage (V)
Figure 9 Rdson vs Vgs

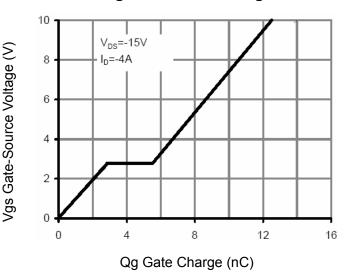


Figure 11 Gate Charge

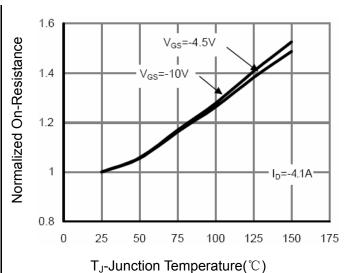
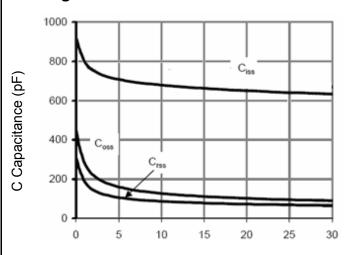


Figure 8 Drain-Source On-Resistance



Vds Drain-Source Voltage (V)

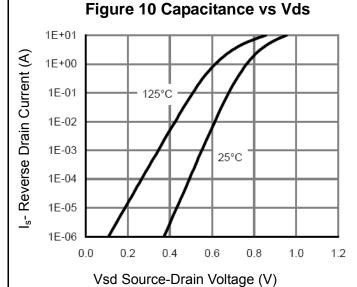
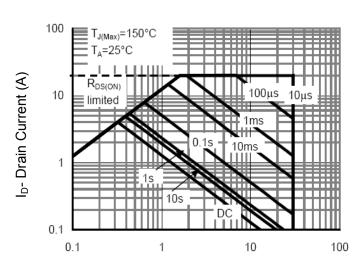


Figure 12 Source- Drain Diode Forward



Vds Drain-Source Voltage (V)

Figure 13 Safe Operation Area

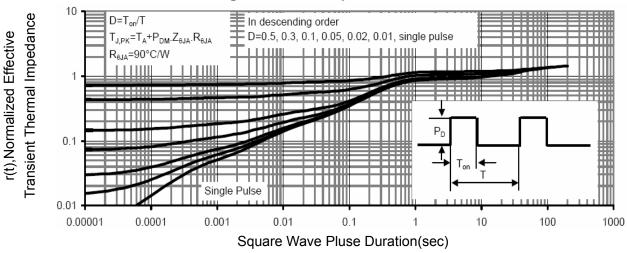
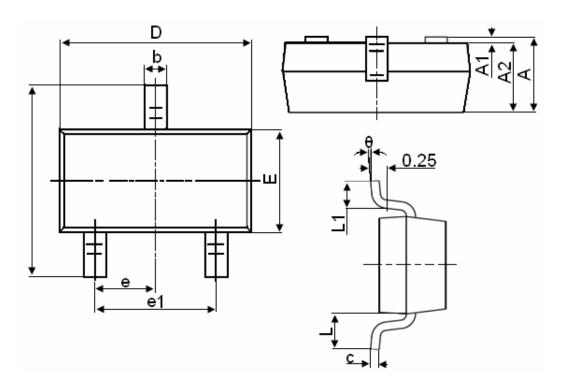


Figure 14 Normalized Maximum Transient Thermal Impedance

SOT-23 Package Information



Symbol	Dimensions in Millimeters				
Symbol	MIN.	MAX.			
Α	0.900	1.150			
A1	0.000	0.100			
A2	0.900	1.050			
b	0.300	0.500			
С	0.080	0.150			
D	2.800	3.000			
E	1.200	1.400			
E1	2.250	2.550			
е		0.950TYP			
e1	1.800	2.000			
L		0.550REF			
L1	0.300	0.500			
θ	0°	8°			

Notes

- 1. All dimensions are in millimeters.
- 2. Tolerance ± 0.10 mm (4 mil) unless otherwise specified
- 3. Package body sizes exclude mold flash and gate burrs. Mold flash at the non-lead sides should be less than 5 mils.
- 4. Dimension L is measured in gauge plane.
- 5. Controlling dimension is millimeter, converted inch dimensions are not necessarily exact.

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